RELIABILITY REPORT

FOR

MAX9021AXK+T

PLASTIC ENCAPSULATED DEVICES

July 25, 2012

MAXIM INTEGRATED PRODUCTS

160 Rio Robles

San Jose, CA 95134

Approved by
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Quality Assurance
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Conclusion

The MAX9021AXK+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX9021/MAX9022/MAX9024 single/dual/quad comparators are optimized for low-power consumption while still providing a fast output response. They are designed for single-supply applications from 2.5V to 5.5V, but can also operate from dual supplies. These comparators have a 3µs propagation delay and consume 2.8µA of supply current per comparator over the -40°C to +125°C operating temperature range. The combination of low-power, single-supply operation down to 2.5V, and ultra-small footprint makes these devices ideal for portable applications. The MAX9021/MAX9022/MAX9024 have 4mV of built-in hysteresis to provide noise immunity and prevent oscillations even with a slow-moving input signal. The input common-mode range extends from the negative supply to within 1.1V of the positive supply. The design of the comparator-output stage substantially reduces switching current during output transitions, eliminating powersupply glitches. The MAX9021 single comparator is available in tiny 5-pin SC70 and SOT23 packages. The MAX9022 dual comparator is available in 8-pin SOT23, µMAX®, and SO packages, and the MAX9024 quad comparator is available in 14-pin TSSOP and SO packages.

II. Manufacturing Information

A. Description/Function:	Micropower, Ultra-Small, Single/Dual/Quad Single-Supply Comparators
B. Process:	S12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Thailand
F. Date of Initial Production:	October 21, 2000

III. Packaging Information

A. Package Type:	5L SC70
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1501-0216 / B
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	324°C/W
K. Single Layer Theta Jc:	115°C/W
L. Multi Layer Theta Ja:	324°C/W
M. Multi Layer Theta Jc:	115°C/W

IV. Die Information

A. Dimensions:	31 X 30 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 79 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 13.9 \times 10^{-9}$

$\lambda = 13.9$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S12 Process results in a FIT Rate of 0.17 @ 25C and 3.00 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (ESD lot N1SABA004B D/C 0222, Latch-up lot SISACQ001A D/C 0413)

The CM48 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX9021AXK+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	79	0	I1SAAQ001D, D/C 0025

Note 1: Life Test Data may represent plastic DIP qualification lots.